

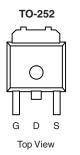
# 2SK3386-Z-E1-AZ-VB Datasheet N-Channel 60-V (D-S) MOSFET

PRODUCT	SUMMARY	
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>
60	0.025 at V <sub>GS</sub> = 10 V	45
	0.030 at V <sub>GS</sub> = 4.5 V	40

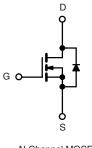
#### FEATURES

- Trench Power MOSFET
- 175 °C Junction Temperature





Drain Connected to Tab



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T <sub>C</sub> =	25 °C, unless othe	rwise noted		
Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V <sub>GS</sub>	± 20	V
Continuous Droin Current /T 175 °CV	T <sub>C</sub> = 25 °C	L	45	
Continuous Drain Current $(T_J = 175 \ ^{\circ}C)^{b}$	T <sub>C</sub> = 100 °C	I <sub>D</sub>	35	
Pulsed Drain Current		I <sub>DM</sub>	100	A
Continuous Source Current (Diode Conduction)		۱ <sub>S</sub>	23	
Avalanche Current		I <sub>AS</sub>	20	
Single Avalanche Energy (Duty Cycle $\leq$ 1 %)	L = 0.1 mH	E <sub>AS</sub>	20	mJ
Maximum Davier Diasin stiller	T <sub>C</sub> = 25 °C	Р	100	W
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3 <sup>a</sup>	vv
Operating Junction and Storage Temperature Range	·	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 10 sec	R <sub>thJA</sub>	18	22	
Maximum Junction-to-Ambient*	Steady State 40 50 °C/W	°C/W			
Maximum Junction-to-Case		R <sub>thJC</sub>	3.2	4	

Notes:

a. Surface Mounted on 1" x 1" FR4 board, t  $\leq$  10 sec.

$\begin{tabular}{ c c c c c } \hline Parameter & Symbol & Test Conditions \\ \hline Static \\ \hline Static \\ \hline Drain-Source Breakdown Voltage & V_{(BR)DSS} & V_{GS} = 0 V, I_D = 250 \ \mu A \\ \hline Gate Threshold Voltage & V_{GS(th)} & V_{DS} = V_{GS}, I_D = 250 \ \mu A \\ \hline Gate Body Leakage & I_{GSS} & V_{DS} = 0 V, V_{GS} = \pm 20 \ V \\ \hline Zero Gate Voltage Drain Current & I_{DSS} & V_{DS} = 60 \ V, V_{GS} = 0 \ V, T_J = 125 \ ^C \\ \hline V_{DS} = 60 \ V, V_{GS} = 0 \ V, T_J = 125 \ ^C \\ \hline V_{DS} = 60 \ V, V_{GS} = 0 \ V, T_J = 175 \ ^C \\ \hline V_{DS} = 60 \ V, V_{GS} = 10 \ V, T_J = 175 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A \\ \hline T_{DS(on)} & V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 125 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 125 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 125 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 125 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 125 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 125 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 125 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 125 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 125 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 125 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 125 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 125 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 175 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 175 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 175 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 175 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 175 \ ^C \\ \hline V_{GS} = 10 \ V, I_D = 15 \ A, T_J = 175 \ ^C \\ \hline V_{GS} = 15 \ V, I_D = 10 \ A \\ \hline \hline T_{GS} = 10 \ V_{GS} = 15 \ V, I_D = 15 \ A \\ \hline \hline T_{GS} = 10 \ V_{GS} = 15 \ V, I_D = 15 \ A \\ \hline \hline T_{GS} = 10 \ V_{GS} = 15 \ V, I_D = 15 \ A \\ \hline \hline T_{GS} = 10 \ V_{GS} = 15 \ V, I_D = 15 \ A \\ \hline \hline \hline \hline T_{GS} = 10 \ V_{GS} = 15 \ V, I_D = 15 \ A \\ \hline \hline \hline \hline T_{GS} = 10 \ V_{GS} = 15 \ V, I_D = 15 \ A \\ \hline \hline$	Min	Тур <sup>а</sup>	Max	Unit	
$ \begin{array}{ c c c c c c } \hline Drain-Source Breakdown Voltage & V_{(BR)DSS} & V_{GS} = 0 \ V, \ I_D = 250 \ \mu A \\ \hline Gate Threshold Voltage & V_{GS(th)} & V_{DS} = V_{GS}, \ I_D = 250 \ \mu A \\ \hline Gate-Body Leakage & I_{GSS} & V_{DS} = 0 \ V, \ V_{GS} = \pm 20 \ V \\ \hline Zero \ Gate \ Voltage \ Drain \ Current & I_{DSS} & V_{DS} = 60 \ V, \ V_{GS} = 0 \ V, \ T_J = 125 \ ^{\circ}C \\ \hline V_{DS} = 60 \ V, \ V_{GS} = 0 \ V, \ T_J = 125 \ ^{\circ}C \\ \hline V_{DS} = 60 \ V, \ V_{GS} = 0 \ V, \ T_J = 175 \ ^{\circ}C \\ \hline On-State \ Drain \ Current^b & I_{D(on)} & V_{DS} = 5 \ V, \ V_{GS} = 10 \ V \\ \hline Drain-Source \ On-State \ Resistance^b & I_{D(on)} & V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C \\ \hline V_{GS} = 4.5 \ V, \ I_D = 10 \ A \\ \hline Forward \ Transconductance^b & g_{fs} & V_{DS} = 15 \ V, \ I_D = 15 \ A \\ \hline \end{array}$				•	
$ \begin{array}{c c} Gate Threshold Voltage & V_{GS}(th) & V_{DS} = V_{GS}, I_D = 250 \ \mu\text{A} \\ \hline Gate Threshold Voltage & I_{GSS} & V_{DS} = 0 \ V, V_{GS} = \pm 20 \ V \\ \hline Gate-Body Leakage & I_{GSS} & V_{DS} = 0 \ V, V_{GS} = \pm 20 \ V \\ \hline V_{DS} = 60 \ V, V_{GS} = 0 \ V \\ \hline V_{DS} = 60 \ V, V_{GS} = 0 \ V \\ \hline V_{DS} = 60 \ V, V_{GS} = 0 \ V, T_J = 125 \ ^{\circ}\text{C} \\ \hline V_{DS} = 60 \ V, V_{GS} = 0 \ V, T_J = 175 \ ^{\circ}\text{C} \\ \hline V_{DS} = 60 \ V, V_{GS} = 0 \ V, T_J = 175 \ ^{\circ}\text{C} \\ \hline V_{GS} = 10 \ V, I_D = 15 \ \text{A} \\ \hline V_{GS} = 10 \ V, I_D = 15 \ \text{A}, T_J = 125 \ ^{\circ}\text{C} \\ \hline V_{GS} = 10 \ V, I_D = 15 \ \text{A}, T_J = 125 \ ^{\circ}\text{C} \\ \hline V_{GS} = 10 \ V, I_D = 15 \ \text{A}, T_J = 125 \ ^{\circ}\text{C} \\ \hline V_{GS} = 4.5 \ V, I_D = 10 \ \text{A} \\ \hline \end{array} $	00				
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	60			V	
$ \begin{array}{c c} V_{DS} = 60 \ V, \ V_{GS} = 0 \ V \\ \hline V_{DS} = 60 \ V, \ V_{GS} = 0 \ V \\ \hline V_{DS} = 60 \ V, \ V_{GS} = 0 \ V, \ T_J = 125 \ ^{\circ}C \\ \hline V_{DS} = 60 \ V, \ V_{GS} = 0 \ V, \ T_J = 175 \ ^{\circ}C \\ \hline V_{DS} = 60 \ V, \ V_{GS} = 0 \ V, \ T_J = 175 \ ^{\circ}C \\ \hline V_{DS} = 60 \ V, \ V_{GS} = 0 \ V, \ T_J = 175 \ ^{\circ}C \\ \hline V_{DS} = 5 \ V, \ V_{GS} = 10 \ V \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C \\ \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C \\ \hline V_{GS} = 4.5 \ V, \ I_D = 10 \ A \\ \hline Forward \ Transconductance^{b} \ g_{fs} \ V_{DS} = 15 \ V, \ I_D = 15 \ A \\ \hline \end{array} $	1.0	2.0	3.0	Unit V nA μA A Ω S PF nC ns	
$ \begin{array}{c c} \mbox{Zero Gate Voltage Drain Current} & I_{DSS} & \hline V_{DS} = 60 \ V, \ V_{GS} = 0 \ V, \ T_J = 125 \ ^{\circ}C & \hline V_{DS} = 60 \ V, \ V_{GS} = 0 \ V, \ T_J = 175 \ ^{\circ}C & \hline V_{DS} = 60 \ V, \ V_{GS} = 0 \ V, \ T_J = 175 \ ^{\circ}C & \hline V_{DS} = 5 \ V, \ V_{GS} = 10 \ V & \hline V_{GS} = 10 \ V, \ I_D = 15 \ A & \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C & \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C & \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C & \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C & \hline V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 175 \ ^{\circ}C & \hline V_{GS} = 4.5 \ V, \ I_D = 10 \ A & \hline \end{array} $			± 100	nA	
$\begin{tabular}{ c c c c c c } \hline & V_{DS} = 60 \ V, \ V_{GS} = 0 \ V, \ T_J = 175 \ ^{\circ}C \\ \hline & V_{DS} = 60 \ V, \ V_{GS} = 0 \ V, \ T_J = 175 \ ^{\circ}C \\ \hline & V_{DS} = 5 \ V, \ V_{GS} = 10 \ V \\ \hline & V_{GS} = 10 \ V, \ I_D = 15 \ A \\ \hline & V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C \\ \hline & V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 125 \ ^{\circ}C \\ \hline & V_{GS} = 10 \ V, \ I_D = 15 \ A, \ T_J = 175 \ ^{\circ}C \\ \hline & V_{GS} = 4.5 \ V, \ I_D = 10 \ A \\ \hline & Forward \ Transconductance^b \ g_{fs} \ V_{DS} = 15 \ V, \ I_D = 15 \ A \\ \hline \end{tabular}$			1		
$ \begin{array}{c c} \text{On-State Drain Current}^{b} & I_{D(on)} & V_{DS} = 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V} \\ \\ \text{Drain-Source On-State Resistance}^{b} & \\ P_{DS(on)} & \hline \\ \hline$			50	μA	
$\frac{V_{GS} = 10 \text{ V}, \text{ I}_D = 15 \text{ A}}{V_{GS} = 10 \text{ V}, \text{ I}_D = 15 \text{ A}}$ $\frac{V_{GS} = 10 \text{ V}, \text{ I}_D = 15 \text{ A}, \text{ T}_J = 125 ^{\circ}\text{C}}{V_{GS} = 10 \text{ V}, \text{ I}_D = 15 \text{ A}, \text{ T}_J = 175 ^{\circ}\text{C}}$ $\frac{V_{GS} = 4.5 \text{ V}, \text{ I}_D = 10 \text{ A}}{V_{GS} = 4.5 \text{ V}, \text{ I}_D = 15 \text{ A}}$			250		
Drain-Source On-State Resistance <sup>b</sup> $r_{DS(on)}$ $V_{GS} = 10 \text{ V}, \text{ I}_D = 15 \text{ A}, \text{ T}_J = 125 ^{\circ}\text{C}$ $V_{GS} = 10 \text{ V}, \text{ I}_D = 15 \text{ A}, \text{ T}_J = 175 ^{\circ}\text{C}$ $V_{GS} = 4.5 \text{ V}, \text{ I}_D = 15 \text{ A}, \text{ T}_J = 175 ^{\circ}\text{C}$ Forward Transconductance <sup>b</sup> $g_{fs}$ $V_{DS} = 15 \text{ V}, \text{ I}_D = 15 \text{ A}$	50			Α	
$\begin{tabular}{ c c c c c c } \hline Drain-Source On-State Resistance^{D} & $r_{DS(on)}$ & $V_{GS} = 10 \text{ V}, \text{ I}_{D} = 15 \text{ A}, \text{ T}_{J} = 175 \ ^{\circ}\text{C}$ & $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 10 \text{ A}$ & $V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 10 \text{ A}$ & $V_{DS} = 15 \text{ V}, \text{ I}_{D} = 15 \text{ A}$ & $V_{DS} = 15 \text{ V}$ & $V_{DS} = 15 $		0.025			
$\frac{V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}, I_J = 175 \text{ °C}}{V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}}$ Forward Transconductance <sup>b</sup> $g_{fs}$ $V_{DS} = 15 \text{ V}, I_D = 15 \text{ A}$		0.055			
Forward Transconductance <sup>b</sup> $g_{fs}$ $V_{DS} = 15 V$ , $I_D = 15 A$		0.069			
		0.030			
Dynamic <sup>a</sup>		20		S	
Input Capacitance C <sub>iss</sub>		1500			
Output Capacitance $C_{oss}$ $V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz$		140		pF	
Reverse Transfer Capacitance C <sub>rss</sub>		60			
Total Gate Charge <sup>c</sup> Q <sub>g</sub>		11	17		
Gate-Source Charge <sup>c</sup> $Q_{gs}$ $V_{DS} = 30 V$ , $V_{GS} = 10 V$ , $I_D = 23 A$		3		nC	
Gate-Drain Charge <sup>c</sup> Q <sub>gd</sub>		3			
Turn-On Delay Time <sup>c</sup> t <sub>d(on)</sub>		8	15		
Rise Time <sup>c</sup> $t_r$ $V_{DD} = 30 \text{ V}, \text{ R}_L = 1.3 \Omega$		15	25	ns	
Turn-Off Delay Time <sup>c</sup> $t_{d(off)}$ $I_D \cong 23$ A, $V_{GEN} = 10$ V, $R_g = 2.5 \Omega$		30	45		
Fall Time <sup>c</sup> t <sub>f</sub>		25	40		
Source-Drain Diode Ratings and Characteristics $(T_C = 25 \degree C)$					
Pulsed Current I <sub>SM</sub>			50	А	
Diode Forward Voltage $V_{SD}$ $I_F = 15 \text{ A}, V_{GS} = 0 \text{ V}$		1.0	1.5	V	
Reverse Recovery Time $t_{rr}$ $I_F = 15 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		I			

Notes:

a. For design aid only; not subject to production testing.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

c. Independent of operating temperature.

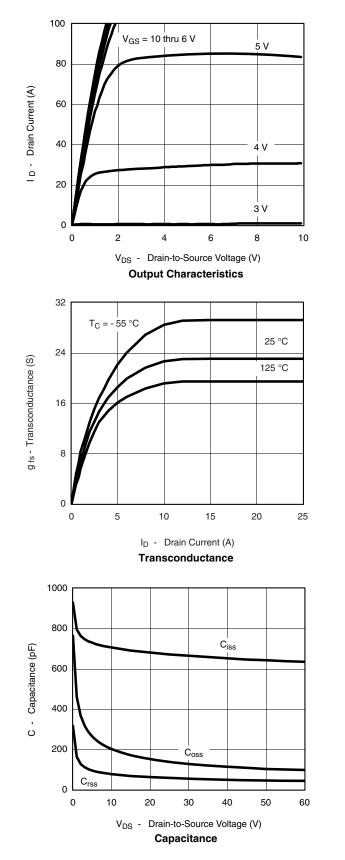
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

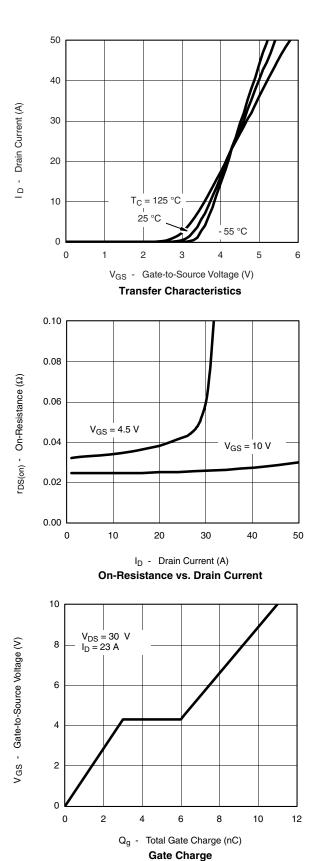
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#### TYPICAL CHARACTERISTICS 25 °C unless noted

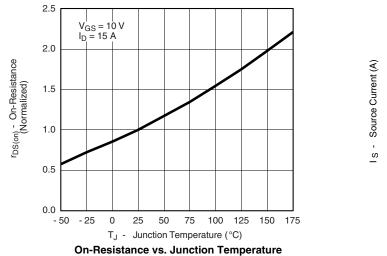


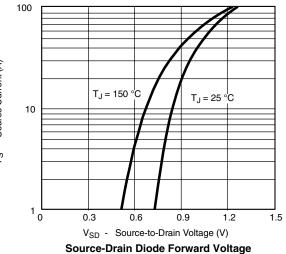


服务热线:400-655-8788



#### TYPICAL CHARACTERISTICS 25 °C unless noted





### 2SK3386-Z-E1-AZ-VB

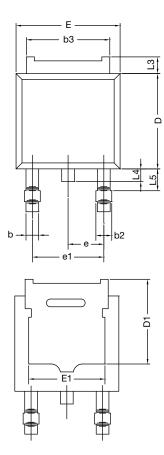


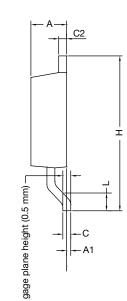
#### **THERMAL RATINGS**





# **TO-252AA CASE OUTLINE**





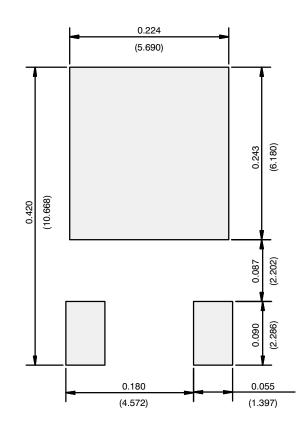
	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56	BSC	0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12- DWG: 534	0247-Rev. M, 7	24-Dec-12			

Note

• Dimension L3 is for reference only.



#### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



# Disclaimer

All products due to improve reliability, function or design or for other reasons, product specifications and data are subject to change without notice.

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